

# **GOLD PLATING:** Worth its Weight?

### **Cost-Saving Opportunities & Strategies for Interconnects**

With rising gold prices showing no signs of slowing, eventual cost increases to products using gold are inevitable. Samtec is actively pursuing opportunities to help offset the impending impact to our interconnect products.



### The Cost of a Plating Choice

Considering that plating can be attributed to nearly 30-40% of the overall cost of a connector, specifying gold plating can have a significant impact, especially with heavier gold options. Alternate materials and lower gold options can provide immediate cost-savings, and potentially help mitigate possible gold-driven price increases in the future.

### Selecting the Right Plating Option



The rugged qualities of gold make it an ideal choice for high-cycle applications, however, heavy gold is often specified when a lower thickness may be sufficient.

Applications requiring less than 100 cycles, for example, could potentially use  $10\mu$ " Au (or less) with adequate reliability, while also providing significant cost-savings. Please contact **ASG@Samtec.com** to discuss your application with a specialist.

In addition to offering a variety of lower gold plating options. Samtec is currently evaluating alternative plating technologies designed to provide excellent performance, along with cost-efficiencies.

-F 3μ" Flash Selective Gold, Matte Tin on tail
 -G 10μ" Gold, 3μ" Gold on Tail
 -L 10μ" Light Selective Gold, Matte Tin on tail
 -S 30μ" Selective Gold, Matte Tin on tail
 100 - 250 (min)

**COMMON GOLD PLATINGS** 

\*Note: Average mating cycles are dependent upon contact style and are not tested to failure. Please review the Series product prints for relevant test reports, test results for cycles, mixed flow gas, and a complete list of plating options.

### ONLINE TOOLS & RESOURCES FOR CONNECTOR SELECTION

Samtec makes it easy to locate and select plating and other options for specific part

numbers with our **Online Product Configurator**, downloadable **Product Prints**, **Test Reports** and **Catalog Pages**.

Additional tools include **Solutionator**\* mated set generators, **Picture Search**, free **3D models** and more. Visit **samtec.com/solutions/digital-tools** to find your ideal product solution.







**MATING CYCLES** 

### **COMING SOON!**

Lower plating option products - in stock and ready for shipment!

# **52M EC GOLD PLATING OPTION UPDATES**

Samtec has recently re-evaluated and updated our plating options for standard catalog parts. Among other adjustments, updates include the addition of lower gold options ( $3\mu$ " Flash Selective Gold and  $10\mu$ " Gold) where applicable.

Visit samtec.com to view options for a specific part number using Samtec's Online Product Configurator, or to download product prints and catalog pages for a specific Series.

Plating PEMOVED from Catalo

## -F Plating ADDED CES CLE **ESHF ESW** FTR HTMS Flexible Stacking MNT MW RSM SLM SMS TFM **TFML** TML **TMS** CC79L CC79R IPL1 MMSD MMSDT MMSS **MMSST** SFM SFMC SFML **SFSD SFSDT** SFSS **SFSST**

-S Plating REMOVED from Catalog Page			
AcceleRate* HD Strips	ADM6	Q Rate <sup>*</sup> Strips	QRF8
	ADF6		QRM8
	APF6	SEARAY"	SEAF
	APM6		SEAM
Edge Rate* Strips	ERF8		SEAF-RA
	ERM8		SEAM-RA
	ERF8-S		SEAM-GP
	ERM8-S		SEAF8
EXTreme Ten60Power™	ET60S		SEAM8
	ET60T		SEAFP
Generate® High-Speed Edge Card Sockets	HSEC1		SEAMP
	HTEC8		SEAMI
	HSEC8-DV	One Piece	SIR1
	HSEC8-RA	Flexible Stacking	SMM
	HSEC8-EM		SSM
	HSEC8-PE		TCSD
	HSEC8-PV		TEM-DH
LP Array <sup>™</sup>	LPAF		TMM-SM
	LPAM		TMM-TH
PCI Express* Sockets	PCIE-LP		TSM
	PCIE-G4	AcceleRate* mP	UDF6
	PCIE-G5		UDM6

# -S Plating REMOVED & -G Plating ADDED UMPS UMPT UMPC UMPCT UMPI UMPI UMPI UMPE

\*Note: Please review the Series product prints for relevant test reports, test results for cycles and mixed flow gas, and a complete list of plating options.

**UMPET** 

CC489

TC146